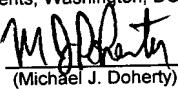


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Dated: December 3, 2002

Signature:


(Michael J. Doherty)

EXPEDITED PROCEDURE

Group Art Unit: 2827

Docket No.: TESSERA 3.0-078 DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Fjelstad et al.

Application No.: 09/020,647

Filed: February 9, 1998

For: METHODS OF MAKING COMPLIANT
SEMICONDUCTOR CHIP PACKAGES

Group Art Unit: 2827

Examiner: D. Graybill

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AMENDMENT UNDER 37 CFR 1.116

Box AF
Commissioner for Patents
Washington, DC 20231

Dear Sir:

The present Amendment After Final is in response to the Final Office Action mailed July 25, 2002, in the above-identified U.S. patent application.

IN THE CLAIMS

42. (Twice Amended) The method according to Claim 35, further including plating a barrier metal atop the contacts of said semiconductor chip, wherein said barrier metal reduces voiding at an interface between the contacts and said bond ribbons.